Product Change Notification: DSNO-22RZBH819

Date:

25-Jun-2026

Product Category:

8-Bit Microcontrollers, KEELOQ® Encoder Devices

Notification Subject:

CCB 8310 Final Notice: Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound material for selected PIC12C508A, PIC12C509A and HCS201 device families available in 8L SOIC (3.90mm) package.

Affected CPNs:

DSNO-22RZBH819_Affected_CPN_06252026.pdf
DSNO-22RZBH819_Affected_CPN_06252026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound material for selected PIC12C508A, PIC12C509A and HCS201 device families available in 8L SOIC (3.90mm) package.

Pre and Post Summary Changes:

	Pre Change	**Post Change**	**Change** (Yes/No)
Assembly Site	Microchip Technology Thailand (Branch) (MMT)	Microchip Technology Thailand (Branch) (MMT)	No
Wire Material	CuPdAu	CuPdAu	No

Die Attach Material	8390A (PFAS-free)	QMI519 (PFAS-free)	CRM-1064L (PFAS-free)	Yes
Molding Compound Material	G600V		G630AY	Yes
Lead-Frame Material	CDA194		CDA194	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying CRM-1064L as additional die attach material and G630AY as additional molding compound material.

Change Implementation Status: In Progress

Estimated First Ship Date: 18 August 2026 (date code: 2634)

Note Below EFSD: Note: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	June 2026					>	**August 2026**				
Work Week	23	24	25	26	27		32	33	34	35	36
Qual Report Availability				x							
Final PCN Issue Date				x							
Estimated Implementation Date									x		

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History: June 25, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_DSNO-22RZBH819_Qual_Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

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Affected Catalog Part Numbers (CPN):

PIC12LC509A-04I/SN

PIC12C509A-04E/SN

PIC12C509AT-04E/SN

PIC12C509A-04I/SNC09

HCS201-I/SN

HCS201T/SN017

HCS201T/SN021

HCS201T-I/SN

HCS201/SN

HCS201T/SN

PIC12C508AT-04E/SN

PIC12C508A-04/SN

PIC12C508AT-04I/SN

PIC12LC508A-04I/SN

PIC12LC508AT-04I/SN168

PIC12C508A-04I/SN

PIC12C508AT-04I/SN123

PIC12LC508A-04/SN

PIC12C508AT-04/SN

PIC12C508AT-04I/SN077

PIC12LC508AT-04I/SN167

PIC12C508AT-04I/SN231

PIC12C508AT-04I/SN221

PIC12C508A-04E/SN

PIC12C509AT-04/SN

PIC12LC509A-04/SN

PIC12C509A-04/SN

PIC12C509A-04I/SN

QUALIFICATION REPORT SUMMARY

RELIABILITY LABORATORY

PCN #: DSNO-22RZBH819

Date:
June 22, 2026

Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound material for selected PIC12C508A, PIC12C509A and HCS201 device families available in 8L SOIC (3.90mm) package. This is a qualification by similarity (QBS).

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Package Qualification Report

Purpose: Qualification of CRM-1064L as an additional die attach material and G630AY as an additional mold compound material for selected PIC12C508A, PIC12C509A and HCS201 device families available in 8L SOIC (3.90mm) package. This is a qualification by similarity (QBS).

CCB No.: 7961.002 (Qual Date: May 29, 2026) and 8310

Misc.	**Assembly site**	MMT
	BD Number	BD-004322-01
	MP Code (MPC)	A7AF94C2XB04
	Part Number (CPN)	PIC12C509A-04E/SN
	Assembly Shipping Media (T/R, Tube/Tray)	MSL1
	Base Quantity Multiple (BQM)	Tube
Lead-Frame	**Paddle size**	95x130
	Material	CDA194
	DAP Surface Prep	Bare Cu
	Treatment	Roughening
	Process	Stamped
	Lead-lock	Yes, locking hole
	Part Number	10100842
	Lead Plating	Matte tin
Bond Wire	**Material**	CuPdAu
Die Attach	**Part Number**	CRM-1064L
	Conductive	Yes
MC	**Part Number**	G630AY
PKG	**PKG Type**	SOIC
	Pin/Ball Count	8
	PKG width/size	150 mils
	Die Size	80.9 x 77.2
	Fab Process (site)	120K MCHP

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Package Qualification Report

Manufacturing Information

MPC	Assembly Lot No.	Package
A7AF94C2XB04	MMT-270400025.000	8L SOIC
A7AF94C2XB04	MMT-270400099.000	8L SOIC
A7AF94C2XB04	MMT-270400100.000	8L SOIC

Conclusion:

Qualification of A7AF9 mask / PIC12C509A-04E/SN product using CuPdAu wire in 8L SOIC 150 mils package at MMT site is qualified for MSL1 at 260ºC as per JEDEC J-STD-020 standard and is passed in accordance with specified JEDEC and Mil Standards

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Package Qualification Report

Moisture Soak Precondition Prior to Stresses

Test Method	JESD22-A113, JEDEC J-STD-020		
Test Condition	**MSL1**: 150ºC 24 hours Bake, 168 hours Moisture Soak at 85ºC/85%RH, 3x Reflow at 260ºC		
Required Sample Size	231 units each lot / 3 lots;		
Lot ID	**R2600443-1** **MMT-270400025.000**	**R2600443-2** **MMT-270400099.000**	**R2600443-3** **MMT-270400100.000**
Electrical Results (Fail / Pass)	0/231	0/231	0/231
Electrical Test Tester: J750	25°C and 125°C		
Result	**Passed**		

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Package Qualification Report

High Temp Storage

Test Method	JESD22-A103		
Test Condition	175°C / 504 hours		
Required Sample Size	45 units / 3 lot;		
Lot ID	**R2600443-1** **MMT-270400025.000**	**R2600443-2** **MMT-270400099.000**	**R2600443-3** **MMT-270400100.000**
Electrical Results (Fail / Pass)	0/45	0/45	0/45
Electrical Test Tester: J750	25°C and 125°C		
Result	**Passed**		

Temperature Cycling

Test Method	JESD22-A104		
Test Condition	-65ºC / +150ºC Air to Air / 500 Cycles		
Required Sample Size	77 units each lot / 3 lots; WBP & IPA		
Lot ID	**R2600443-1** **MMT-270400025.000**	**R2600443-2** **MMT-270400099.000**	**R2600443-3** **MMT-270400100.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
WBP (Fail / Pass)	0/5	N/A	N/A
Electrical Test Tester: J750	125°C		
Result	**Passed**		

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Package Qualification Report

Biased HAST

Test Method	JESD22-A110		
Test Condition	+130ºC / 85%RH / 96 hours / Bias Voltage: 5.5V		
Required Sample Size	77 units each lot / 3 lots; IPA		
Lot ID	**R2600443-1** **MMT-270400025.000**	**R2600443-2** **MMT-270400099.000**	**R2600443-3** **MMT-270400100.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: J750	25°C and 125°C		
Result	**Passed**		

Unbiased HAST

Test Method	JESD22-A118		
Test Condition	+130ºC / 85%RH / 96 hours		
Required Sample Size	77 units each lot / 3 lots; IPA		
Lot ID	**R2600443-1** **MMT-270400025.000**	**R2600443-2** **MMT-270400099.000**	**R2600443-3** **MMT-270400100.000**
Electrical Results (Fail / Pass)	0/77	0/77	0/77
Electrical Test Tester: J750	25°C		
Result	**Passed**		

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Package Qualification Report

Solderability (0 hr.) Method 1: Dip and Look

Test Method	J-STD-002 / JESD22B-102
Test Condition / Criteria	Pb-free 8 hours Steam age. Dip at 245ºC, 100% leads >95% lead coverage
Required Sample Size	22 units / 1 lot
Visual Result (Fail / Pass)	0/22 (Passed)

Wire Pull

Test Method	Mil. Std. 883-2011
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 (Passed)

Bond Shear

Test Method	CDF-AEC-Q100-001
Test Criteria	Bond Strength Data Assembly
Required Sample Size	5 units / 1 lot
Result (Fail / Pass)	0/5 (Passed)